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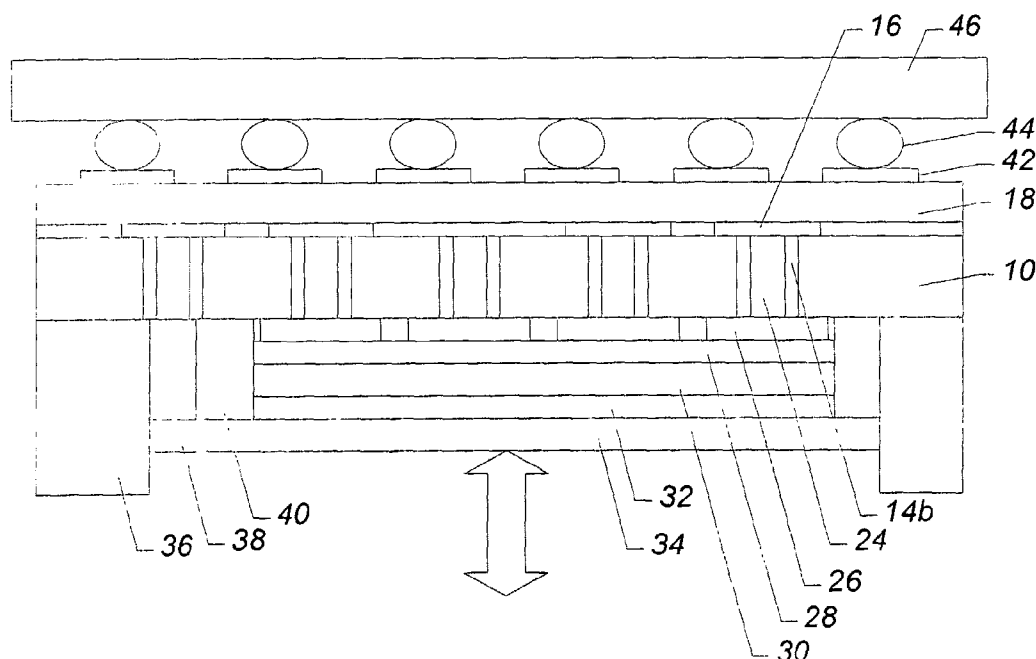
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(54) Title: SPATIAL LIGHT MODULATOR DISPOSED ON A SEMICONDUCTOR SUBSTRATE WITH A MICROPROCESSOR CIRCUIT FOR DRIVING THE MODULATOR DISPOSED ON THE OPPOSED SIDE OF THE SUBSTRATE



(57) Abstract: An integrated circuit may have a spatial light modulator (30) formed on one side of a semiconductor support (10) and a microprocessor (18) formed on the opposite side. The microprocessor (18) and the spatial light modulator may communicate with one another through electrical connections (24) which extend completely through the semiconductor support (10). The microprocessor (18) may be contacted using bump packaging techniques (44).



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